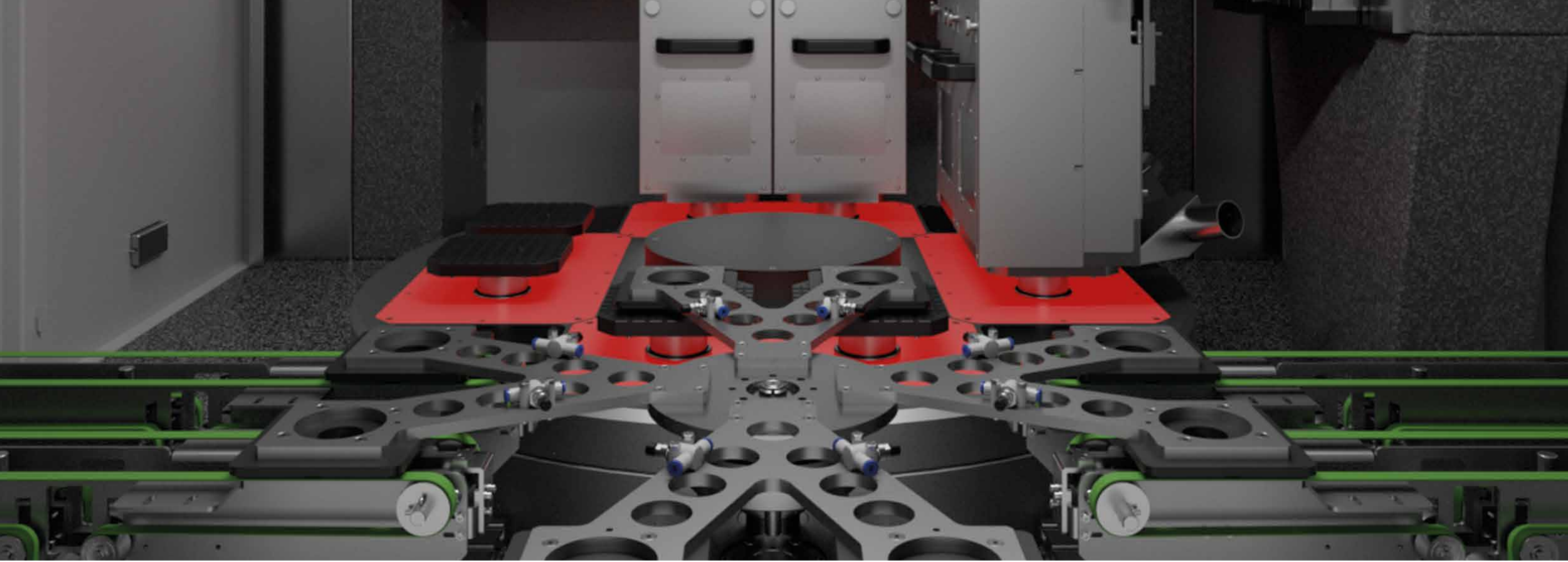
INNOLAS
solutions

INNOVATION FOR THE
NEXT GENERATION

ILS-TTnx

NEXT GENERATION TURNTABLE MACHINE

POWERFUL LASER SYSTEM
FOR MICRO MATERIAL PROCESSING

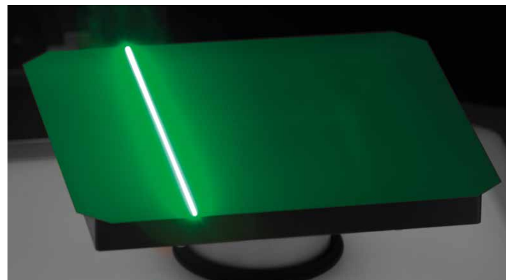


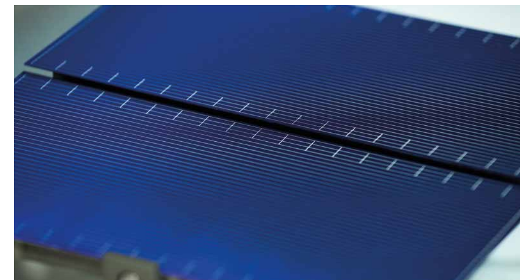
FEATURES

- Multi scanner setup
- Automatic camera calibration
- Automated routines for reference runs
- Automated process control
- Stand alone and production line integrated systems
- 3-, 5- or even 8-Point alignment methods available (wafer edges or fiducials)

OPTIONS

- CAD file import
- SQL data base for process and event tracking
- MES interface (SECS GEM PV2)
- Integrated process metrology
- Fully-automatic handling (production)





APPLICATIONS	Laser Contact Opening for PERC, Laser Doped Selective Emitter, Front side LCO, Laser Direct Cleaving
ACCURACY	< +/-35 µm (1 sigma) < +/-10 µm optionally < +/-2 µm repeatability
SUBSTRATE	Dimension up to 161 x 161 mm Thickness > 100 µm mono or poly crystalline silicon square/ pseudo square
AVAILABLE LASER SOURCES	Wavelength: 1064, 1030, 532, 515, 355 nm Pulse: µs, ns, ps, fs
THROUGHPUT	6000 wafer per hour

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PRODUCT PRESENTATION

Specification subject to change. InnoLas Solutions GmbH, 10/ 2017